

TOSHIBA Multi-Chip Device
Silicon P-Channel MOS Type (U-MOS II) + N-Channel MOS Type (Planer)

SSM6E01TU

Load Switch Applications

- P-channel MOSFET and N-channel MOSFET incorporated into one package.
- Low power dissipation due to P-channel MOSFET that features low R_{DS (ON)} and low-voltage operation

Q1 Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-Source voltage		V _{DS}	-12	V
Gate-Source voltage		V _{GSS}	±12	V
Drain current	DC	I _D	-1.0	A
	Pulse	I _{DP} (Note 2)	-2.0	

Q2 Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-Source voltage		V _{DS}	20	V
Gate-Source voltage		V _{GSS}	10	V
Drain current	DC	I _D	0.05	A
	Pulse	I _{DP} (Note 2)	0.2	

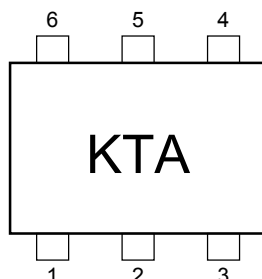
Maximum Ratings (Q1, Q2 common) (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Drain power dissipation	P _D (Note 1)	0.5	W
Channel temperature	T _{ch}	150	°C
Storage temperature range	T _{stg}	-55~150	°C

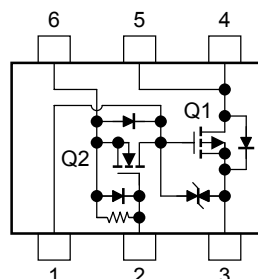
Note 1: Mounted on an FR4 board (25.4 mm × 25.4 mm × 1.6 t, Cu pad: 645 mm²)

Note 2: Pulse width limited by maximum channel temperature.

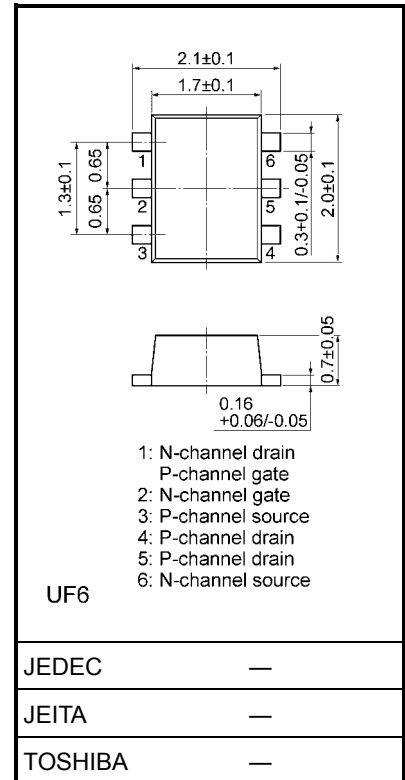
Marking



Equivalent Circuit (top view)



Unit: mm



Weight: 7.0 mg (typ.)

Handling Precaution

This product has a MOS structure and is sensitive to electrostatic discharge. When handling individual devices (that have not yet been mounted on a PCB), ensure that the environment is protected against static electricity. Operators should wear anti-static clothing, containers and other objects which may come into direct contact with devices should be made of anti-static materials.

Thermal resistance $R_{th(j-a)}$ and drain power dissipation P_D vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration.

Q1 Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward voltage (diode)	V_{DSF}	$I_{DR} = 1.0 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	1.2	V
Gate leakage current	I_{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$	—	—	± 1	μA
Drain-Source breakdown voltage	$V_{(BR)DSS}$	$I_D = -1 \text{ mA}, V_{GS} = 0$	-12	—	—	V
Drain cut-off current	I_{DSS}	$V_{DS} = -12 \text{ V}, V_{GS} = 0$	—	—	-1	μA
Gate threshold voltage	V_{th}	$V_{DS} = -3 \text{ V}, I_D = -0.1 \text{ mA}$	-0.4	—	-1.1	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = -3 \text{ V}, I_D = -0.5 \text{ A}$ (Note 3)	1.3	2.5	—	S
Drain-Source ON resistance	$R_{DS(ON)}$	$I_D = -0.5 \text{ A}, V_{GS} = -4 \text{ V}$ (Note 3)	—	125	160	m Ω
		$I_D = -0.5 \text{ A}, V_{GS} = -2.5 \text{ V}$ (Note 3)	—	180	240	
Input capacitance	C_{iss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	310	—	pF

Note 3: Pulse test

Q2 Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = 10 \text{ V}, V_{DS} = 0$	—	—	15	μA
Drain-Source breakdown voltage	$V_{(BR)DSS}$	$I_D = 0.1 \text{ mA}, V_{GS} = 0$	20	—	—	V
Drain cut-off current	I_{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0$	—	—	1	μA
Gate threshold voltage	V_{th}	$V_{DS} = 3 \text{ V}, I_D = 0.1 \text{ mA}$	0.7	—	1.3	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 3 \text{ V}, I_D = 10 \text{ mA}$ (Note 3)	25	50	—	mS
Drain-Source ON resistance	$R_{DS(ON)}$	$I_D = 10 \text{ mA}, V_{GS} = 2.5 \text{ V}$ (Note 3)	—	4	10	Ω
Input capacitance	C_{iss}	$V_{DS} = 3 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	11	—	pF
Gate-Source resistance	R_{GS}	$V_{GS} = 0 \sim 10 \text{ V}$	0.7	1.0	1.3	M Ω

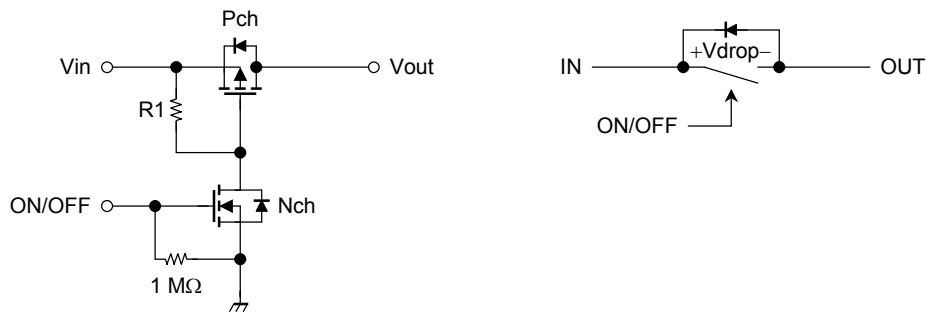
Note 3: Pulse test

Precaution

V_{th} can be expressed as voltage between gate and source when low operating current value is $I_D = \pm 100 \mu\text{A}$ for this product. For normal switching operation, $V_{GS(ON)}$ requires higher voltage than V_{th} and $V_{GS(OFF)}$ requires lower voltage than V_{th} . (Relationship can be established as follows: $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$)

Please take this into consideration for using the device. 2.5 V or higher is recommended for V_{GS} voltage to turn on the N-channel MOSFET of this product.

Load Switch Application



Load Switch Ratings (Ta = 25°C)

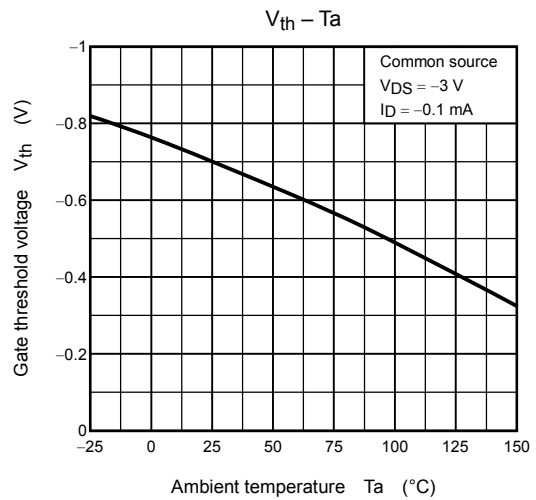
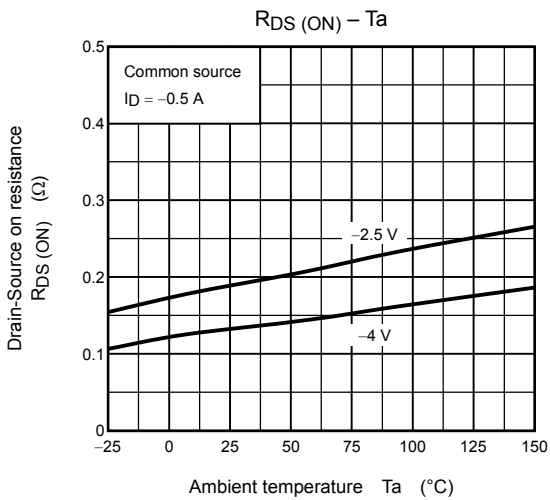
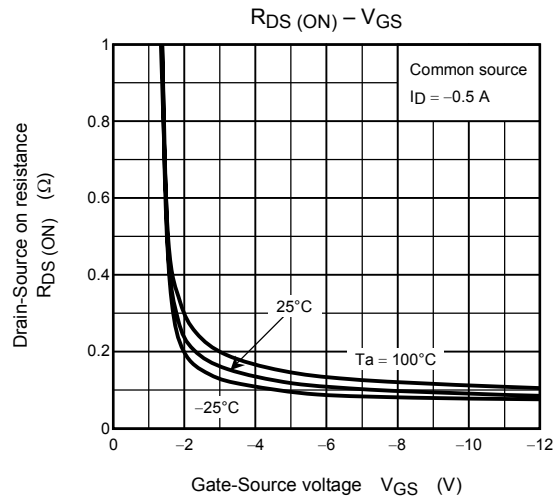
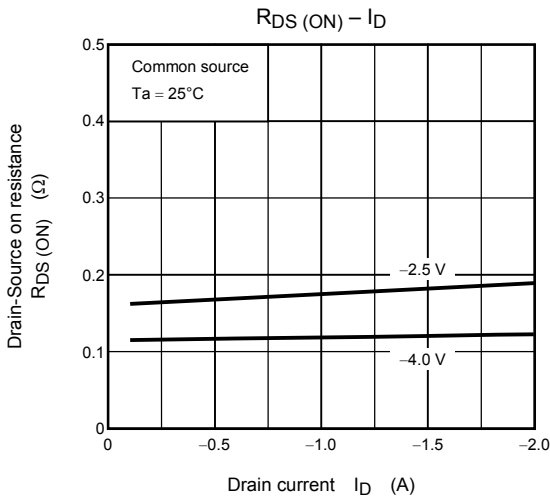
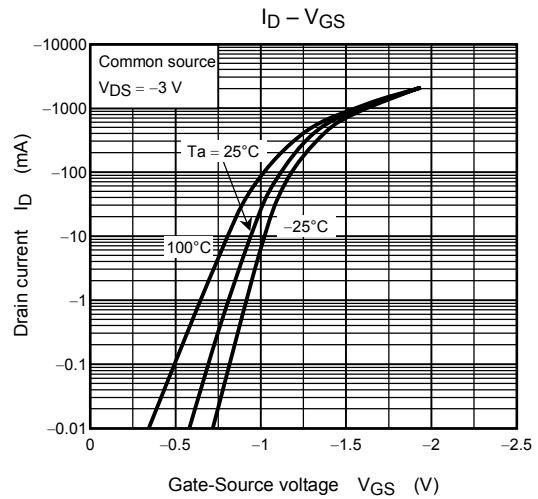
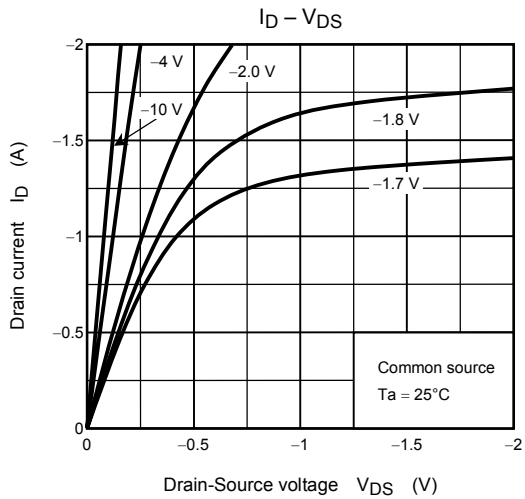
Characteristics	Symbol	Rating	Unit
Input voltage	V_{in}	2.5~12	V
ON/OFF voltage	$V_{on/off}$	2.5~10	V
Load current (DC)	I_L	1	A
Load current (pulse)	I_{LP} (Note 4)	2	A
Channel temperature	T_{ch}	150	°C

Note 4: Pulse width limited by maximum channel temperature.

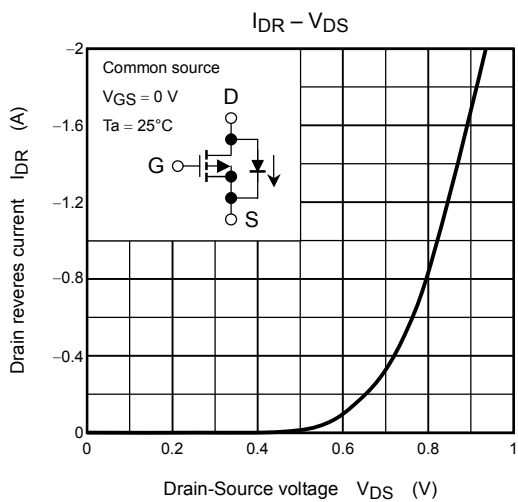
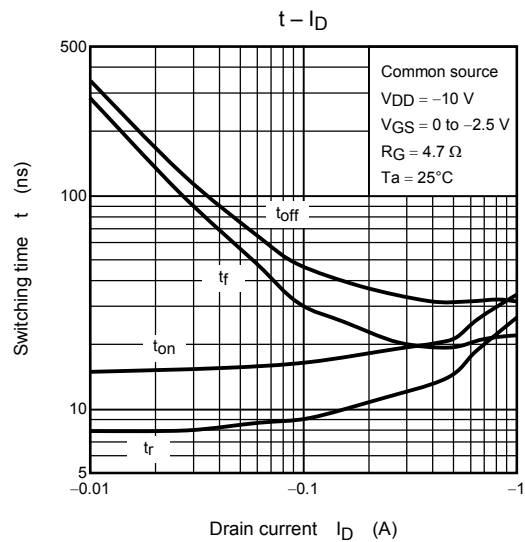
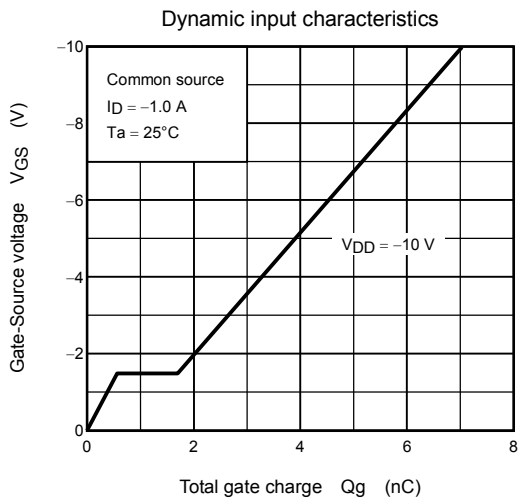
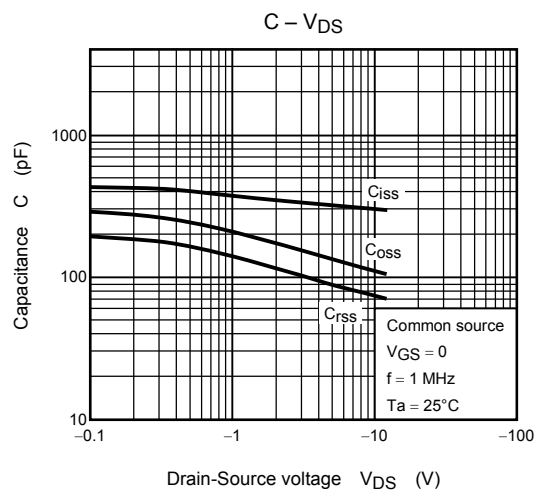
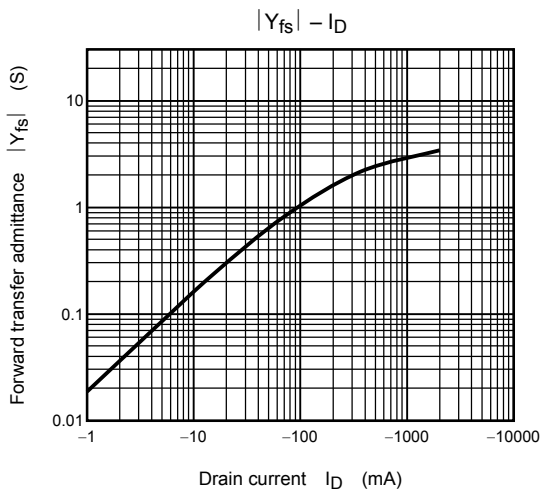
Load Switch Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Leakage current	I_{FL}	$V_{in} = 8\text{ V}, V_{ON/OFF} = 0$	—	—	1	μA
P-channel drop voltage	$V_{DROP (1)}$	$V_{in} = 3.0\text{ V}, V_{ON/OFF} = 2.5\text{ V}, I_L = 0.5\text{ A}$	—	0.09	0.12	V
	$V_{DROP (2)}$	$V_{in} = 5.0\text{ V}, V_{ON/OFF} = 2.5\text{ V}, I_L = 1.0\text{ A}$	—	0.13	0.16	
N-channel drive voltage	$V_{on/off}$	$V_{DS} = 3\text{ V}, I_D = 0.1\text{ mA}$	0.7	—	1.3	V

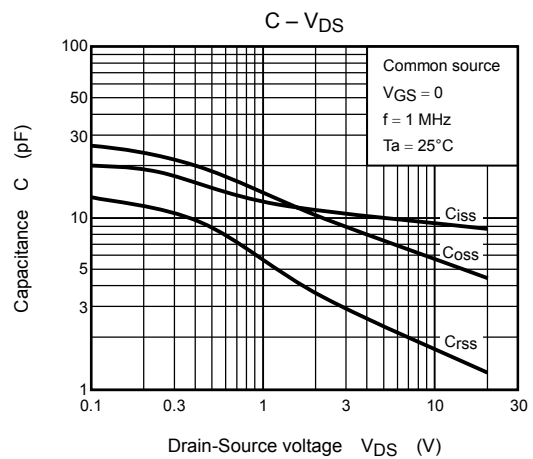
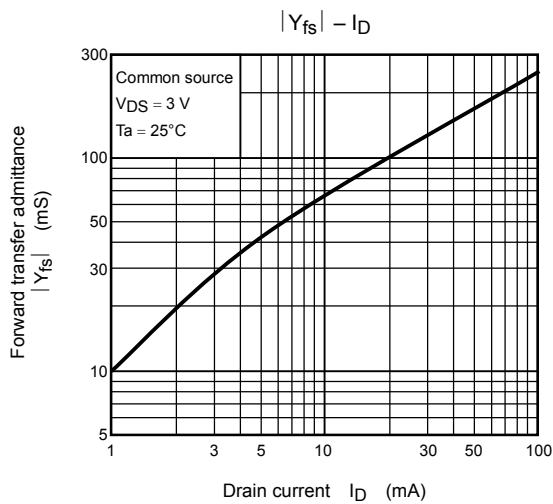
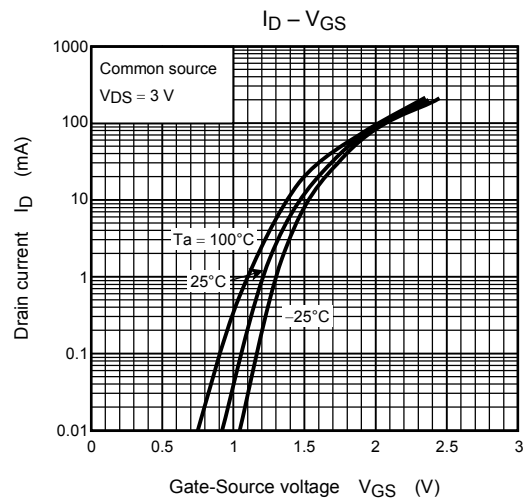
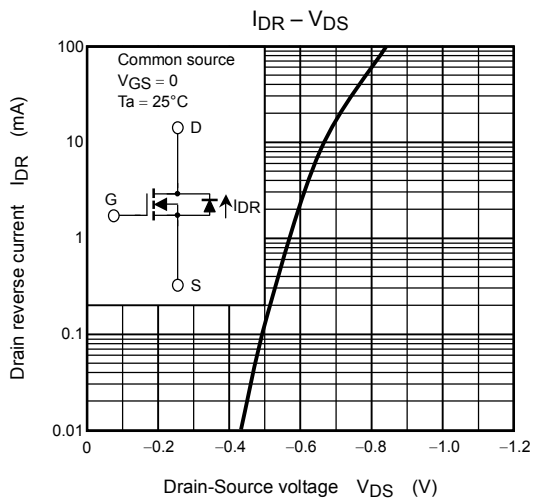
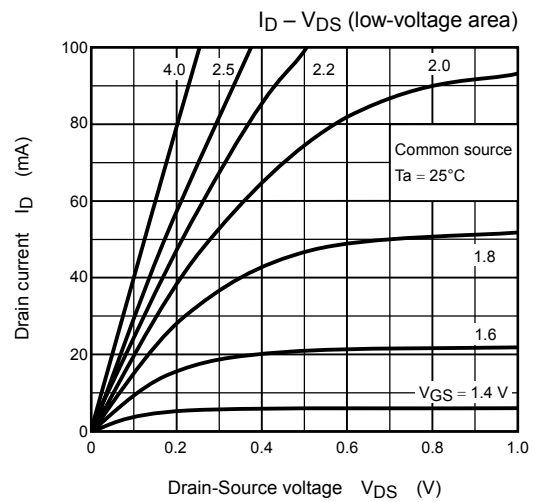
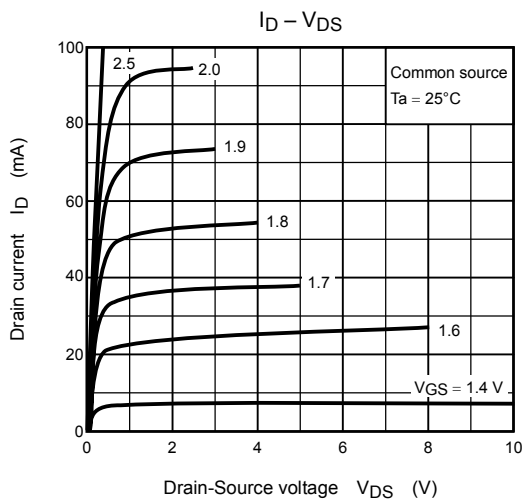
Q1 (Pch MOSFET)



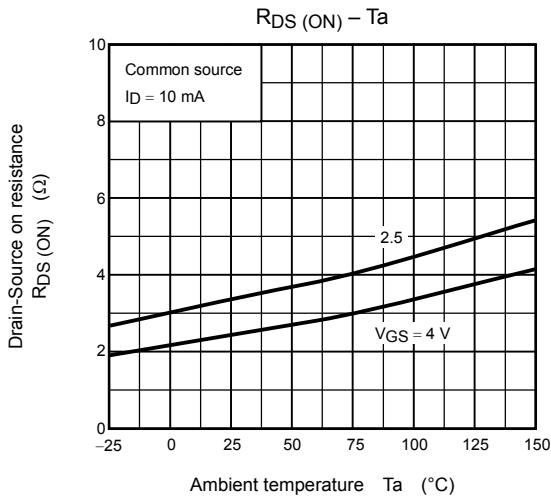
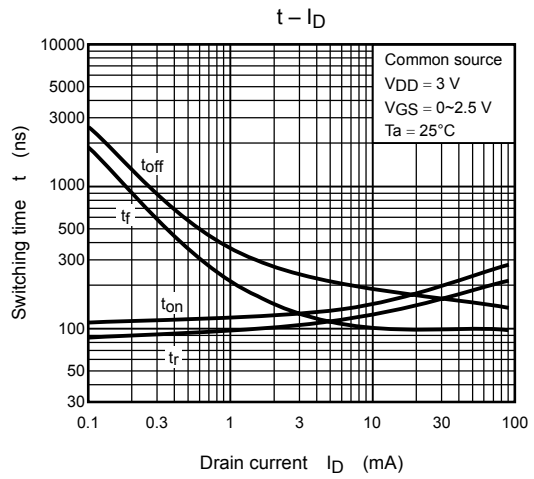
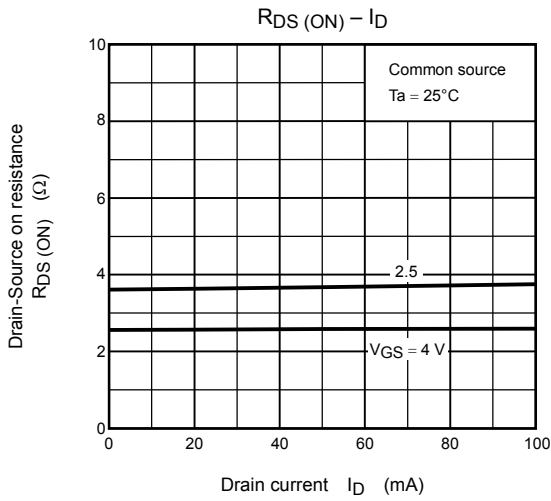
Q1 (Pch MOSFET)



Q2 (Nch MOSFET)



Q2 (Nch MOSFET)



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